

CD54/74HC4543

CD54/74HCT4543

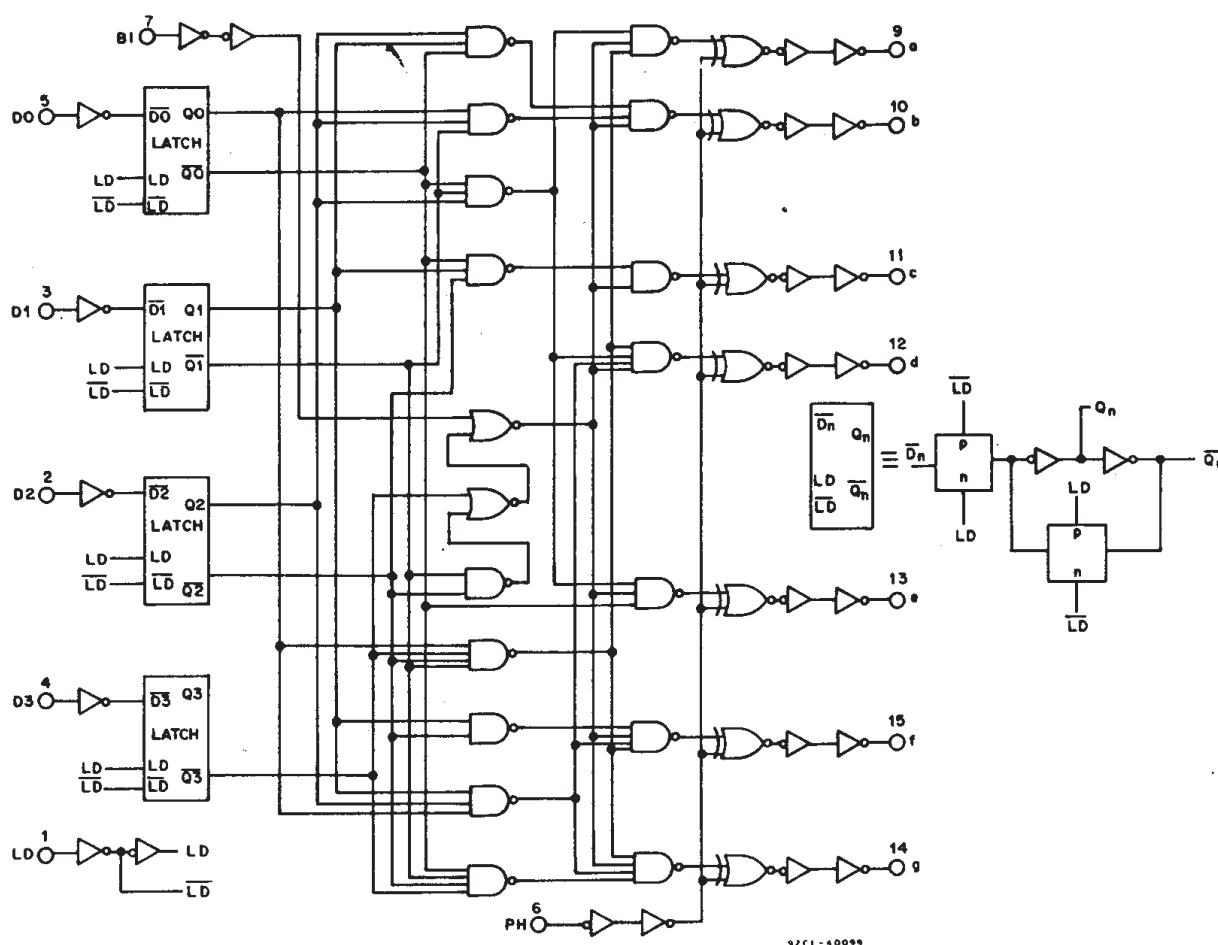


Fig. 1 - Logic diagram.

MAXIMUM RATINGS, Absolute-Maximum Values:**DC SUPPLY-VOLTAGE, (V_{CC}):**

(Voltages referenced to ground) -0.5 to +7 V

DC INPUT DIODE CURRENT, I_{IK} (FOR $V_i < -0.5$ V OR $V_i > V_{CC} + 0.5$ V) ± 20 mADC OUTPUT DIODE CURRENT, I_{OK} (FOR $V_o < -0.5$ V OR $V_o > V_{CC} + 0.5$ V) ± 20 mADC DRAIN CURRENT, PER OUTPUT (I_o) (FOR -0.5 V $< V_o < V_{CC} + 0.5$ V) ± 25 mADC V_{CC} OR GROUND CURRENT (I_{CC}) ± 50 mA**POWER DISSIPATION PER PACKAGE (P_D):**For $T_A = -40$ to $+60^\circ\text{C}$ (PACKAGE TYPE E) 500 mWFor $T_A = +60$ to $+85^\circ\text{C}$ (PACKAGE TYPE E) Derate Linearly at 8 mW/ $^\circ\text{C}$ to 300 mWFor $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPE F,H) 500 mWFor $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPE F,H) Derate Linearly at 8 mW/ $^\circ\text{C}$ to 300 mWFor $T_A = -40$ to $+70^\circ\text{C}$ (PACKAGE TYPE M) 400 mWFor $T_A = +70$ to $+125^\circ\text{C}$ (PACKAGE TYPE M) Derate Linearly at 6 mW/ $^\circ\text{C}$ to 70 mW**OPERATING-TEMPERATURE RANGE (T_A):**PACKAGE TYPE F,H -55 to $+125^\circ\text{C}$ PACKAGE TYPE E,M -40 to $+85^\circ\text{C}$ **STORAGE TEMPERATURE (T_{stg}):**..... -65 to $+150^\circ\text{C}$ **LEAD TEMPERATURE (DURING SOLDERING):**At distance $1/16 \pm 1/32$ in. (1.59 ± 0.79 mm) from case for 10 s max. $+265^\circ\text{C}$ Unit inserted into a PC Board (min. thickness $1/16$ in., 1.59 mm) with solder contacting lead tips only $+300^\circ\text{C}$

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RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range (For T_A =Full Package Temperature Range) V_{CC} .*			
CD54/74HC Types	2	6	V
CD54/74HCT Types	4.5	5.5	
DC Input or Output Voltage, V_i , V_o	0	V_{CC}	V
Operating Temperature, T_A :			
CD74 Types	-40	+85	°C
CD54 Types	-55	+125	
Input Rise and Fall Times, t_r , t_f :			
at 2 V	0	1000	ns
at 4.5 V	0	500	
at 6 V	0	400	

*Unless otherwise specified, all voltages are referenced to Ground.

SWITCHING CHARACTERISTICS ($V_{CC}=5$ V, $T_A=25^\circ$ C, Input $t_r, t_f=6$ ns)

CHARACTERISTIC		C_L (pF)	TYPICAL VALUES		UNITS
			HC	HCT	
Propagation Delay:					
D_n to Output	t_{PLH} t_{PHL}	15	28	33	ns
LD to Output	t_{PLH} t_{PHL}	15	31	32	
BI to Output	t_{PLH} t_{PHL}	15	22	27	
PH to Output	t_{PLH} t_{PHL}	15	17	27	
Power Dissipation Capacitance*	C_{PD}	—	52	54	pF

* C_{PD} is used to determine the dynamic power consumption, per package.

$P_D = C_{PD} V_{CC}^2 f_i + \sum C_L V_{CC}^2 f_o$ where f_i = input frequency

f_o = output frequency

C_L = output load capacitance

V_{CC} = supply voltage.

PRE-REQUISITE FOR SWITCHING FUNCTION

CHARACTERISTIC	TEST CONDITIONS V_{CC} (V)	LIMITS												UNITS	
		25° C				-40° C to +85° C				-55° C to +125° C					
		HC		HCT		74HC		74HCT		54HC		54HCT			
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.		
Setup Time, D_n to LD	t_{SU}	2	60	—	—	—	75	—	—	—	90	—	—	—	ns
		4.5	12	—	12	—	15	—	15	—	18	—	18	—	
		6	10	—	—	—	13	—	—	—	15	—	—	—	
Hold Time, D_n to LD	t_H	2	30	—	—	—	40	—	—	—	45	—	—	—	
		4.5	6	—	8	—	8	—	10	—	9	—	12	—	
		6	5	—	—	—	7	—	—	—	8	—	—	—	
Latch Disable Pulse Width,	t_W	2	50	—	—	—	65	—	—	—	75	—	—	—	
		4.5	10	—	10	—	13	—	13	—	15	—	15	—	
		6	9	—	—	—	11	—	—	—	13	—	—	—	

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STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CD74HC4543/CD54HC4543										CD74HCT4543/CD54HCT4543										UNITS
	TEST CONDITIONS			74HC/54HC TYPES			74HC TYPES		54HC TYPES		TEST CONDITIONS		74HCT/54HCT TYPES			74HCT TYPES		54HCT TYPES			
	V _I V	I _O mA	V _{CC} V	+25°C			-40/ +85°C		-55/ +125°C		V _I V	V _{CC} V	+25°C			-40/ +85°C		-55/ +125°C			
				Min	Typ	Max	Min	Max	Min	Max			Min	Typ	Max	Min	Max	Min	Max		
High-Level Input Voltage V _{IH}			2	1.5	—	—	1.5	—	1.5	—	—	4.5 to 5.5	2	—	—	2	—	2	—	V	
Low-Level Input Voltage V _{IL}			2	—	—	0.5	—	0.5	—	0.5	—	4.5 to 5.5	—	—	0.8	—	0.8	—	0.8	V	
High-Level Output Voltage V _{OH} CMOS Loads	V _{IL} or V _{IH}	-0.02	2	1.9	—	—	1.9	—	1.9	—	V _{IL} or V _{IH}	4.5	4.4	—	—	4.4	—	4.4	—	V	
TTL Loads Non-Standard Output	V _{IL} or V _{IH}	-1 -1.3	4.5 6	3.98 5.48	— —	— —	3.84 5.34	— —	3.7 5.2	—	V _{IL} or V _{IH}	4.5	3.98	—	—	3.84	—	3.7	—	V	
Low-Level Output Voltage V _{OL} CMOS Loads	V _{IL} or V _{IH}	0.02	2	—	—	0.1	—	0.1	—	0.1	V _{IL} or V _{IH}	4.5	—	—	0.1	—	0.1	—	0.1	V	
TTL Loads Non-Standard Output	V _{IL} or V _{IH}	1 1.3	4.5 6	— —	— —	0.26 0.26	— —	0.33 0.33	— —	0.4 0.4	V _{IL} or V _{IH}	4.5	—	—	0.26	—	0.33	—	0.4	V	
Input Leakage Current I _I	V _{CC} or Gnd		6	—	—	±0.1	—	±1	—	±1	Any Voltage Between V _{CC} & Gnd	5.5	—	—	±0.1	—	±1	—	±1	μA	
Quiescent Device Current I _{CC}	V _{CC} or Gnd	0	6	—	—	8	—	80	—	160	V _{CC} or Gnd	5.5	—	—	8	—	80	—	160	μA	
Additional Quiescent Device Current per input pin: 1 unit load ΔI _{CC} *											V _{CC} -2.1	4.5 to 5.5	—	100	360	—	450	—	490	μA	

*For dual-supply systems theoretical worst case ($V_i = 2.4$ V, $V_{cc} = 5.5$ V) specification is 1.8 mA.

HCT Input Loading Table

Input	Unit Loads*
D0, D1, D2	1
D3, BI	0.5
PH	1.25
LD	1.5

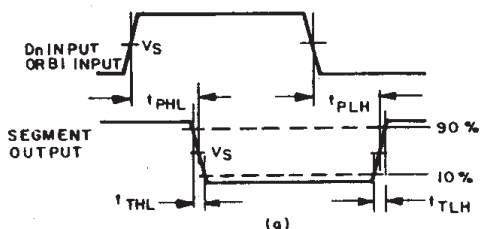
*Unit Load is ΔI_{cc} limit specified in Static Characteristics Chart, e.g., 360 μA max. @ 25°C.

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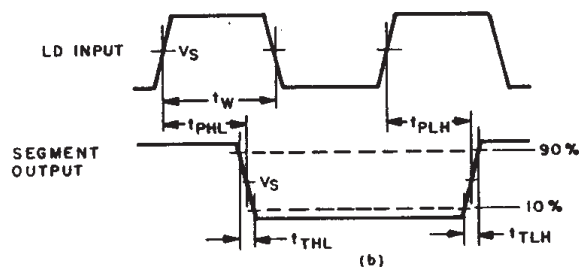
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SWITCHING CHARACTERISTICS ($C_L=50$ pF, Input $t_r, t_f=6$ ns)

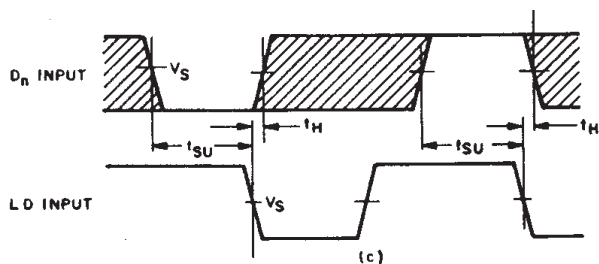
CHARACTERISTIC		V _{CC}	LIMITS												UNITS
			25°C				-40°C to +85°C				-55°C to +125°C				
			HC		HCT		74HC		74HCT		54HC		54HCT		
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Propagation Delay, D _n to Output	t _{PLH}	2	—	340	—	—	—	425	—	—	—	510	—	—	ns
	t _{PHL}	4.5	—	68	—	80	—	85	—	100	—	102	—	120	
		6	—	58	—	—	—	72	—	—	—	87	—	—	
LD to Output	t _{PLH}	2	—	370	—	—	—	465	—	—	—	555	—	—	ns
	t _{PHL}	4.5	—	74	—	77	—	93	—	96	—	111	—	116	
		6	—	63	—	—	—	79	—	—	—	94	—	—	
BI to Output	t _{PLH}	2	—	265	—	—	—	330	—	—	—	400	—	—	ns
	t _{PHL}	4.5	—	53	—	66	—	66	—	83	—	80	—	99	
		6	—	45	—	—	—	56	—	—	—	68	—	—	
PH to Output	t _{PLH}	2	—	200	—	—	—	250	—	—	—	300	—	—	ns
	t _{PHL}	4.5	—	40	—	66	—	50	—	83	—	60	—	99	
		6	—	34	—	—	—	43	—	—	—	51	—	—	
Transition Time	t _{TLH}	2	—	250	—	—	—	315	—	—	—	375	—	—	ns
	t _{THL}	4.5	—	50	—	50	—	63	—	63	—	75	—	75	
		6	—	43	—	—	—	54	—	—	—	64	—	—	
Input Capacitance	C _i		—	10	—	10	—	10	—	10	—	10	—	10	pF



(a) WAVEFORMS SHOWING THE ADDRESS AND BLANKING (D_n , BI) TO OUTPUT PROPAGATION DELAYS AND THE OUTPUT TRANSITION TIMES.



(b) WAVEFORMS SHOWING THE LATCH DISABLE INPUT (LD) TO OUTPUT PROPAGATION DELAYS AND THE OUTPUT TRANSITION TIMES.



NOTE:
THE SHADED AREAS INDICATE WHEN THE INPUT IS PERMITTED TO CHANGE FOR PREDICTABLE OUTPUT PERFORMANCE.

(c) WAVEFORMS SHOWING THE ADDRESS (D_n) TO LATCH DISABLE (LD) INPUT SET-UP AND HOLD TIMES.

92CM-40103

	54/74HC	54/74HCT
Input Level	V_{CC}	3 V
Switching Voltage, V_s	50% V_{CC}	1.3 V

Fig. 2 - AC waveforms.

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APPLICATION CIRCUITS

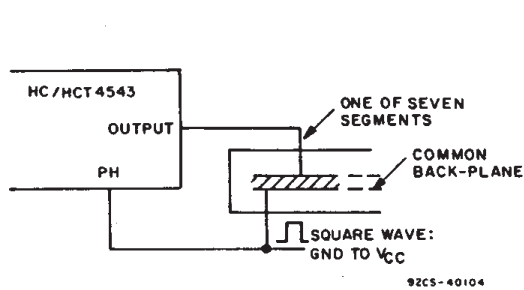


Fig. 3 - Connection to liquid-crystal (LCD) display readout.

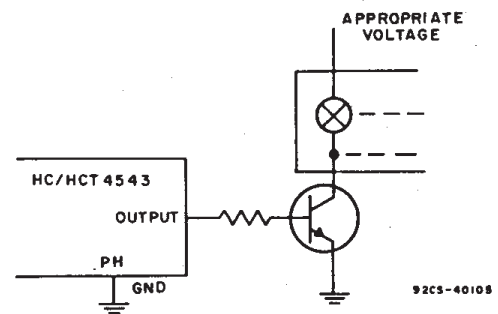


Fig. 4 - Connection to incandescent display readout.

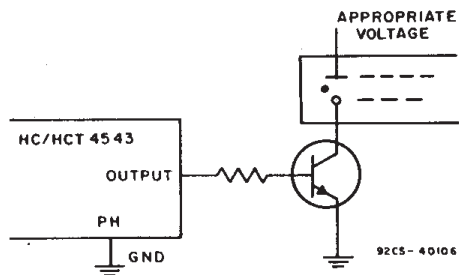


Fig. 5 - Connection to gas-discharge display readout.

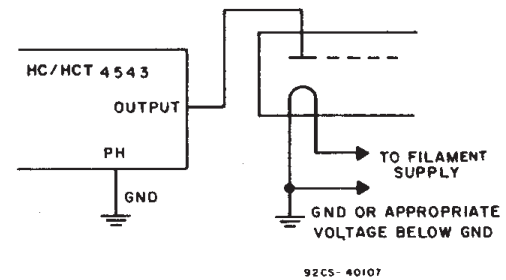


Fig. 6 - Connection to fluorescent display readout.

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